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## Materials Declaration Form

<b>IPC Form Type *</b>	<b>1752</b> Distribute	<b>Version</b>	<b>2</b>
<b>Sectionals *</b>	Material Info Manufacturing Info	<b>Sectionals *</b>	A-D  *: Required Field

Supplier Information			
<b>Company Name *</b>	<b>STMicroelectronics</b>	<b>Response Date *</b>	<b>2016-05-04</b>
<b>Contact Name *</b>	Refer to Supplier Comment section		Refer to Supplier Comment section
<b>Authorized Representative *</b>	<b>Floriana San Biagio</b>	<b>Representative Title</b>	<b>AMG MD CHAMPION</b>
<b>Representative Phone *</b>	Refer to Supplier Comment section	<b>Representative Email *</b>	Refer to Supplier Comment section
<b>Supplier Comment</b>	Online Technical Support - STMicroelectronics : <a href="http://www.st.com/web/en/support/support.html">http://www.st.com/web/en/support/support.html</a>		

**Uncertainty Statement**

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**Legal Statement**

<b>Supplier Acceptance *</b>	<b>true</b>	<b>Legal Declaration *</b>	<b>Standard</b>
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**Legal Statement**

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
	IDK7*V994ARY	A	BO2A	2016-05-04
Amount	UoM	Unit type	ST ECOPACK Grade	
130.00	mg	Each	ECOPACK® 3	
	Comment	ECOPACK® 3 is STMicroelectronics trade name for ROHS compliant device without use of any ROHS exemption and without Halogen nor Antimony		

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
1	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
NAC	Nicke/Palladium/Gold (Ni/Pd/Au)	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
DSO	8.6x3.9x1.52	14	gull wing	
Comment	Package: K7 SO 14 .15 TO JEDEC MS-012; MDF valid for TSV994IYDT			

QueryList : ROHS directive 2011/65/EU _ July 2011	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	true
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	false
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	false
Exemption Id.	Description

QueryList : REACH-17th December 2015				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration						Mfr Item Name	IDK7*V994ARY					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die	Other inorganic materials	1.413	mg	supplier	die	Silicon (Si)	7440-21-3		1.340	mg	948337	10308
				supplier	metallization	Aluminium (Al)	7429-90-5		0.012	mg	8492	92
				supplier	metallization	Titanium (Ti)	7440-32-6		0.001	mg	708	8
				supplier	metallization	Tungsten (W)	7440-33-7		0.001	mg	708	8
				supplier	Passivation	Silicon Nitride	12033-89-5		0.003	mg	2123	23
				supplier	Passivation	Silicon Oxide	7631-86-9		0.028	mg	19816	215
Leadframe	Copper & its alloys	39.076	mg	supplier	glass coating	Glass: Silicon Dioxide	7631-86-9		0.028	mg	19816	215
				supplier	alloy	Copper (Cu)	7440-50-8		37.783	mg	966911	290638
				supplier	alloy	Iron (Fe)	7439-89-6		0.889	mg	22751	6838
				supplier	alloy	Iron Phosphide (FeP)	26508-33-8		0.054	mg	1382	415
				supplier	alloy	Zinc (Zn)	7440-66-6		0.047	mg	1203	362
				supplier	metallization	Nickel (Ni)	7440-02-0		0.278	mg	7113	2138
				supplier	metallization	Palladium (Pd)	7440-05-3		0.009	mg	230	69
				supplier	metallization	Gold (Au)	7440-57-5		0.008	mg	205	62
Die attach	Other Organic Materials	0.522	mg	supplier	metallization	Silver (Ag)	7440-22-4		0.008	mg	205	62
				supplier	glue	Silver (Ag)	7440-22-4		0.475	mg	909962	3654
				supplier	glue	acrylate	Proprietary		0.026	mg	49808	200
				supplier	glue	Methacrylate	Proprietary		0.021	mg	40230	162
Bonding wires	Other inorganic materials	0.101	mg	supplier	wire	Copper (Cu)	7440-50-8		0.101	mg	1000000	777
Encapsulation	Other Organic Materials	88.888	mg	supplier	mold compound	Silica, vitreous	60676-86-0		76.977	mg	866000	592131
				supplier	mold compound	Epoxy Resin	Proprietary		6.667	mg	75005	51285
				supplier	mold compound	Phenol Resin	Proprietary		4.444	mg	49995	34185
				supplier	mold compound	Carbon black	1333-86-4		0.444	mg	4995	3415
				supplier	mold compound	Bismuth (Bi)	7440-69-9		0.356	mg	4005	2738